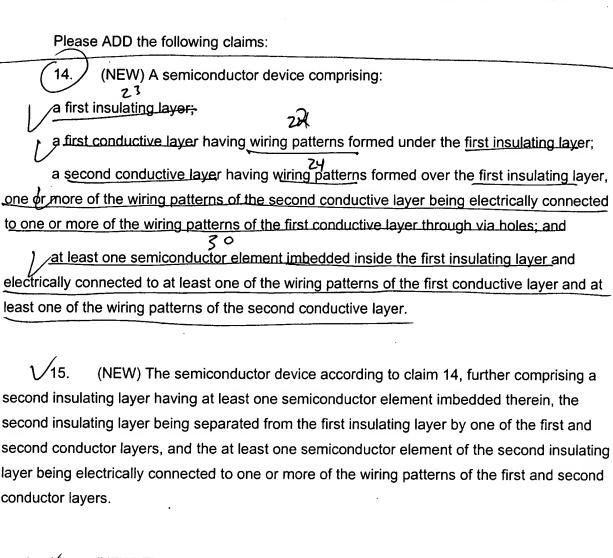
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the wiring patterns of the first conductor layer are electrically connected to one or more of the wiring patterns of the second conductor layer.

a first insulating layer formed over a first conductor layer, the first insulating layer having at least one semiconductor element imbedded therein and the first conductor layer having wiring patterns therein; and

(NEW) A semiconductor device comprising:

a second insulating layer formed over a second conductor layer, the second insulating layer and conductor layer being formed over the first insulating layer and first conductor layer, the second insulating layer having at least one semiconductor element imbedded therein and